

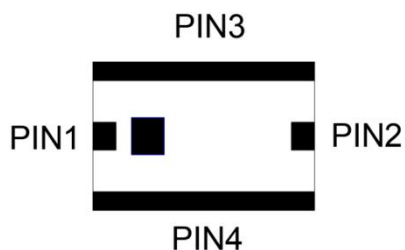
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

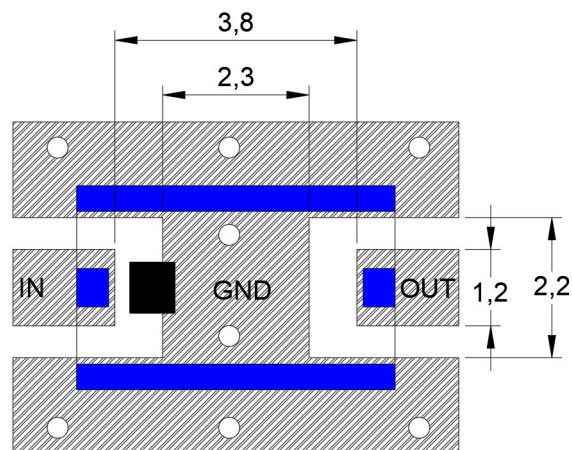
NO.	Parameter	Frequency (MHz)	SPEC	
			Min.	Max.
1	Insertion Loss (dB)	730~770		3.5
2	Ripple (dB)	730~770		0.5
3	Attenuation (dB)	DC~590	50	
		910~1800	50	
4	VSWR	730~770		1.3
5	Phase linearity	730~770	$\pm 5^\circ$	
6	Multiple amplitude consistency(dB)	730~770		0.5
7	Phase Consistency	730~770	$\pm 5^\circ$	
8	In/Output Impedance (Ω)		50	

Construction



PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

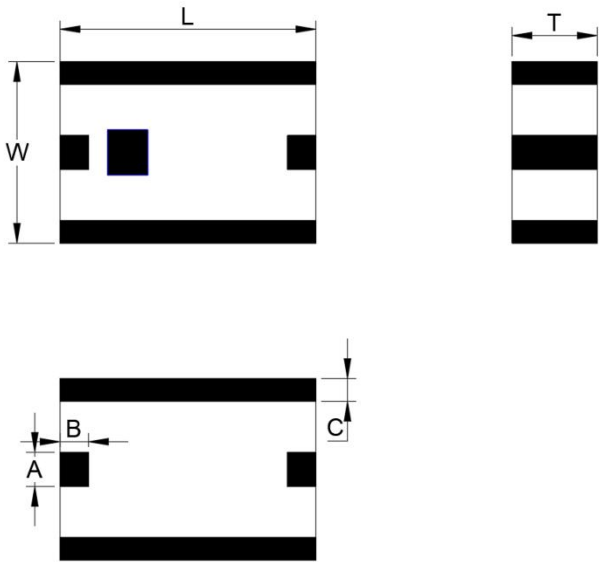
Mounting Considerations



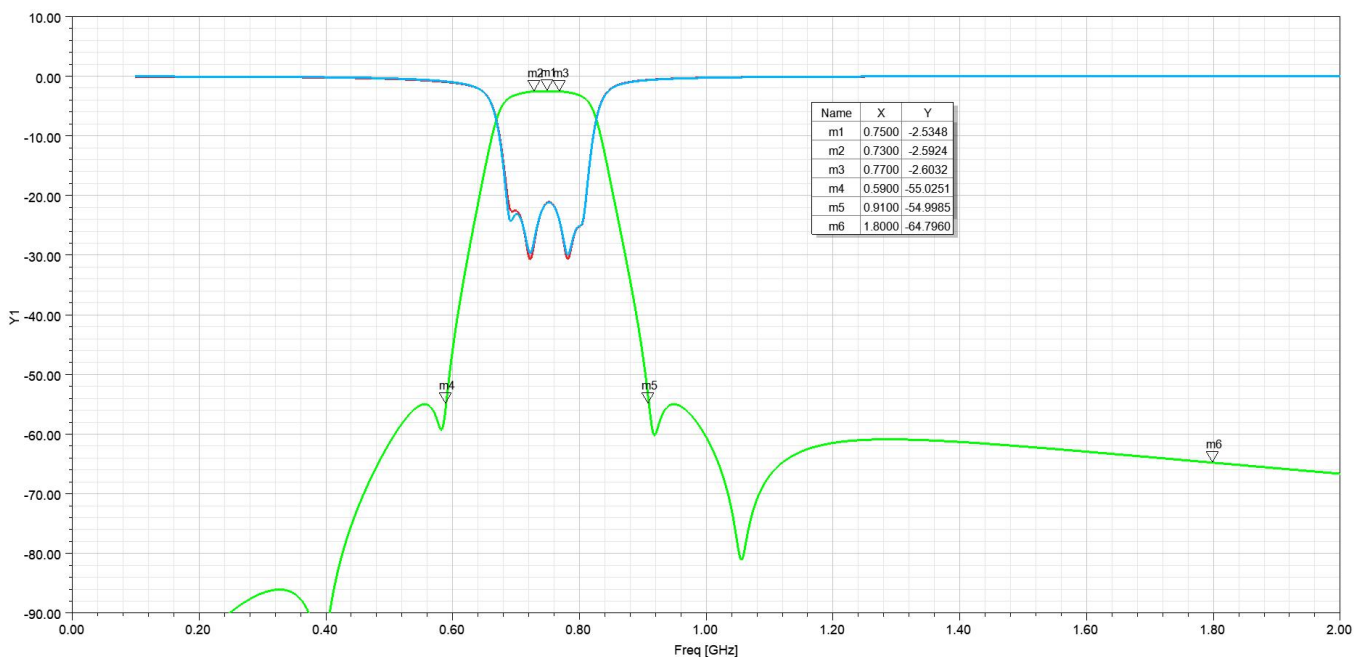
Unit: mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

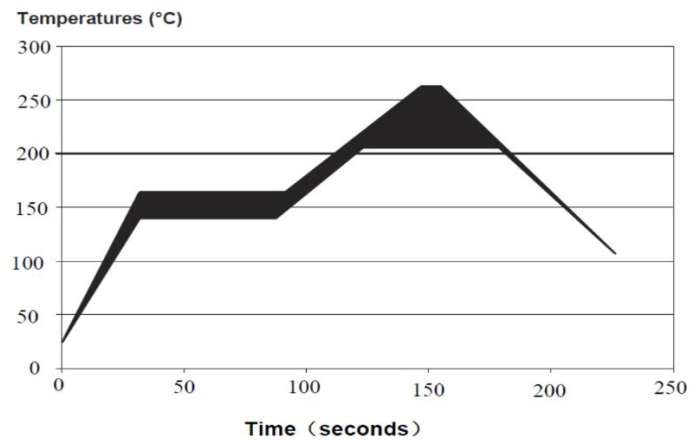
Dimensions

Figure	Symbol	Dimension (mm)
	L	5.00±0.20
	W	3.20±0.20
	T	1.50±0.20
	A	0.60±0.10
	B	0.40±0.10
	C	0.40±0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.